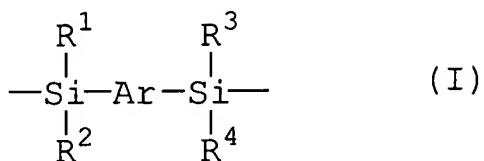


Complete Set of Claims

- [1] 1(currently amended) A composition for formation of etching stopper layer, comprising a silicon-containing polymer, wherein 5% to 100% by mole, based on the total number of moles of silicon contained in the silicon-containing polymer in the composition, of silicon is contained in a disilylbenzene structure.
- [2] 2(currently amended) The composition for formation of etching stopper layer according to claim 1, wherein said silicon-containing polymer has been produced by polymerizing a compound having a disilylbenzene structure and an aromatic group-containing compound.
- [3] 3(currently amended) A silicon-containing material for formation of etching stopper layer, comprising a disilylbenzene structure formed by curing a silicon-containing polymer, wherein 5% to 100% by mole, based on the total number of moles of silicon contained in the silicon-containing material, of silicon is contained in a disilylbenzene structure.
- [4] 4(currently amended) A semiconductor device comprising, as an etching stopper layer, a silicon-containing material for formation of etching stopper layer according to claim 3.
- [5] 5(currently amended) A process for producing a semiconductor device, comprising the steps of: forming an insulating layer and an etching stopper layer on a substrate; removing part of the insulating layer by dry etching; and filling an electrically conductive material into a groove or hole thus formed, wherein said etching stopper layer is formed by curing a composition comprising a silicon-containing polymer, wherein 5% to 100% by mole, based on the total number of

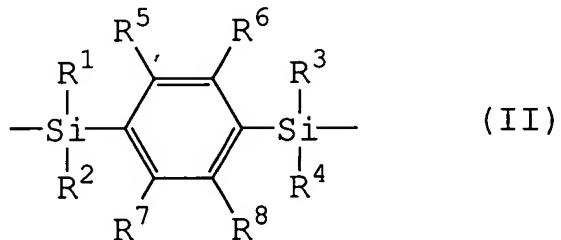
moles of silicon contained in the silicon-containing polymer, of silicon is contained in a disilylbenzene structure.

6(new). The composition of claim 1, where the disilylbenzene structure is represented by formula (I)



wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group, and Ar represents an aryl group.

7(new) The composition of claim 1, where the disilylbenzene structure is represented by formula (II)



wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group; and R⁵ to R⁸ are independently selected from hydrogen, a C₁ to C₃ alkyl group, a halogen atom, a C₁ to C₃ alkoxide group, and a C₁ to C₃ amino group.

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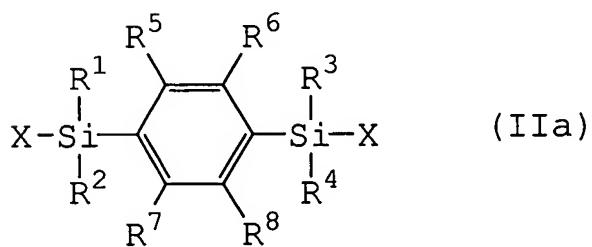
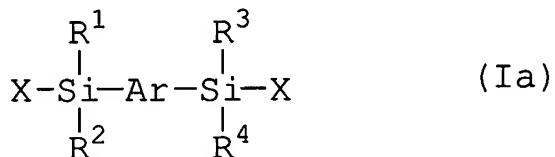
8(new) The composition of claim 1, where the polymer further comprises a comonomeric unit.

9(new) The composition of claim 8, where the comonomeric unit comprises an aromatic group.

10(new) The composition of claim 8, where the comonomeric unit is derived from a monomer selected from phenyltrichlorosilane, diphenyldichlorosilane, methyltrichlorosilane, and methylhydrodichlorosilane.

11(new) The composition of claim 1, where the composition further comprises an additional polymer.

12(new) The composition of claim 2, where the compound having a disilylbenzene structure is represented by formula (Ia) or (IIa)



wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group, and Ar represents an aryl group; and R⁵ to R⁸ are independently selected from hydrogen, a C₁ to C₃

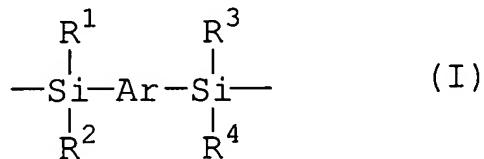
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alkyl group, a halogen atom, a C₁ to C₃ alkoxide group, and a C₁ to C₃ amino group; and, X's, which may be same or different, represented by a halogen atom or a hydroxyl group.

13(new) The composition of claim 2, where the compound having the silylbenzene structure is selected from 1,4-bis(dimethylchlorosilyl) benzene, 1,4-bis(hydroxydimethylchlorosilyl)benzene, and 1,4-bis(diethylchlorosilyl)benzene.

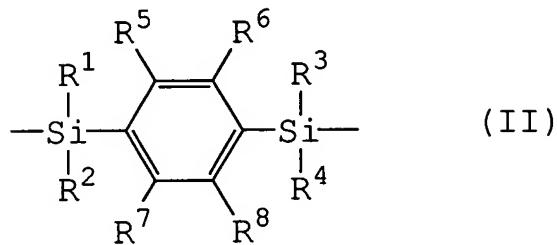
14(new) The composition of claim 2, where the aromatic group containing compound is selected from phenyltrichlorosilane, diphenyldichlorosilane, methyltrichlorosilane, and methylhydrodichlorosilane.

15(new) The silicon-containing material of claim 3, where the disilylbenzene structure is represented by formula (I)



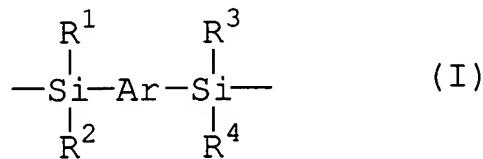
wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group, and Ar represents an aryl group.

16(new) The silicon-containing material of claim 3, where the disilylbenzene is represented by formula (II),



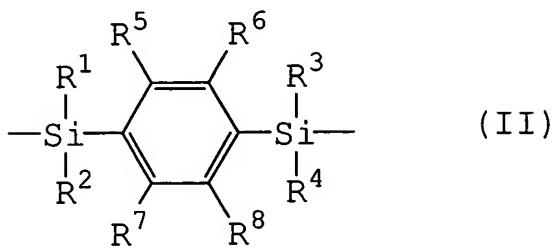
wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group; and R⁵ to R⁸ are independently selected from hydrogen, a C₁ to C₃ alkyl group, a halogen atom, a C₁ to C₃ alkoxide group, and a C₁ to C₃ amino group.

17(new) The semiconductor device according to claim 4, where the disilylbenzene structure is represented by formula (I)



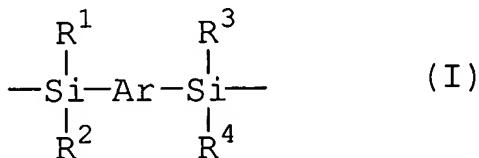
wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group, and Ar represents an aryl group.

18(new) The semiconductor device according to claim 4, where the disilylbenzene structure is represented by formula (II),



wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group; and R⁵ to R⁸ are independently selected from hydrogen, a C₁ to C₃ alkyl group, a halogen atom, a C₁ to C₃ alkoxide group, and a C₁ to C₃ amino group.

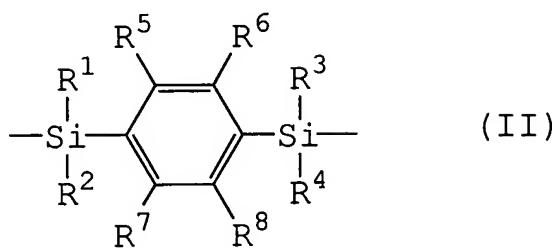
19(new) The process of claim 5, where the disilylbenzene structure is represented by formula (I),



wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group, and Ar represents an aryl group.

20(new) The process of claim 5, where the disilylbenzene structure is represented by formula (II),

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wherein R¹ to R⁴ each independently are selected from hydrogen, an alkyl group, an alkenyl group, a cycloalkyl group, an aryl group, an aralkyl group, an alkylamino group, and an alkylsilyl group; and R⁵ to R⁸ are independently selected from hydrogen, a C₁ to C₃ alkyl group, a halogen atom, a C₁ to C₃ alkoxide group, and a C₁ to C₃ amino group.

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